

LOW TEMPERATURE WAFER-LEVEL MICRO-ENCAPSULATION

ABSTRACT

A method and apparatus are provided for encapsulated micro-devices. More particularly, Microelectromechanical Systems (MEMS) switches are encapsulated. The method and apparatus involve the creation of a cage structure over the micro-devices and the application of a low-temperature liquid protective material onto the cage and subsequent curing to form a hermetic micro-encapsulation. The technique and devices employ the use of conventional semiconductor manufacturing equipment that greatly increase productivity and reduces costs over more conventional techniques and devices for protect similar micro-devices.

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